

PART INFORMATION	
Mfg Item Number	MCIMX6DP5EYM1AA
Mfg Item Name	624 21*21*1.45 P0.8
SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-04-16
Response Document ID	00MEK00239D001A1.1
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com
DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	
MANUFACTURING	
Mfg Item Number	MCIMX6DP5EYM1AA
Mfg Item Name	624 21*21*1.45 P0.8
Version	ALL
Weight	1.178100
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.</p>
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
<p>List of Freescale Accepted Exemptions</p> <p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>	

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Underfill	0.0147	Solvents, additives, and other materials	4,4'-Diamino-3,3'-diethyl-diphenylmethane	19900-65-3		g	110000	11			
Underfill		Bismuth/Bismuth Compounds	Bismuth nitrate	10361-44-1	0.0000147	g	1000	0.1	1372	0.1372	
Underfill		Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3	0.0001176	g	8000	0.8	12	0.0012	
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6	0.002058	g	140000	14	99	0.0099	
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5	0.00147	g	100000	10	1746	0.1746	
Underfill		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.0000147	g	1000	0.1	1247	0.1247	
Underfill		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6	0.000588	g	40000	4	12	0.0012	
Underfill		Glass	Silica, vitreous	60676-86-0	0.00882	g	600000	60	499	0.0499	
Solder Balls - Lead Free	0.3024					g			7486	0.7486	
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8	0.01374559	g	45455	4.5455			
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4	0.00896435	g	29544	2.9544	11667	1.1667	
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5	0.27989006	g	924901	92.4901	7693	0.7693	
Pb-free Bumped Semiconductor D	0.0489					g			237407	23.7407	
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0	0.0002445	g	5000	0.5	207	0.0207	
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4	0.00015404	g	3150	0.315	130	0.013	
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5	0.00424697	g	86850	8.685	3604	0.3604	
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-	0.0004401	g	9000	0.9	373	0.0373	
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-	0.04381439	g	896000	89.6	37190	3.719	
Organic Substrate, Halogen-free	0.8121					g					
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7	0.01199959	g	14776	1.4776	10185	1.0185	
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8	0.8833556	g	472030	47.203	325400	32.54	
Organic Substrate, Halogen-free		Plastics/polymers	Epikote 862	28064-14-4	0.068109	g	71554	7.1554	49324	4.9324	
Organic Substrate, Halogen-free		Plastics/polymers	Formaldehyde, polymer with 2-methylphenol, glycidyl ether	64425-89-4	0.01859059	g	22892	2.2892	15780	1.578	
Organic Substrate, Halogen-free		Lead/Lead Compounds	Lead	7439-92-1	0.00007065	g	87	0.0087	59	0.0059	
Organic Substrate, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4	0.031732	g	39074	3.9074	26934	2.6934	
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3	0.19435746	g	239327	23.9327	164975	16.4975	
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9	0.01665942	g	20514	2.0514	14140	1.414	
Organic Substrate, Halogen-free		Metals	Tin, metal	7440-31-5	0.00012344	g	152	0.0152	104	0.0104	
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-	0.0019263	g	2372	0.2372	1635	0.1635	
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-51-2	0.09519599	g	117222	11.7222	80804	8.0804	

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MCIMX6DP5EYM1AA_IPC1752_v11.xml

http://www.freescale.com/mcds/MCIMX6DP5EYM1AA_IPC1752A.xml